

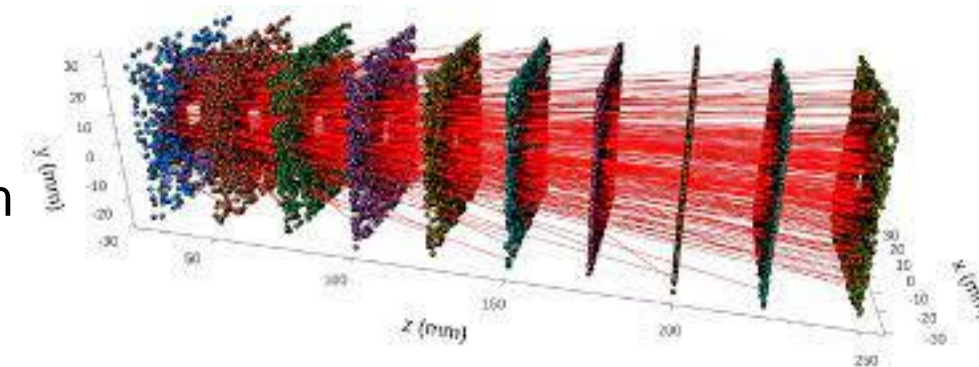
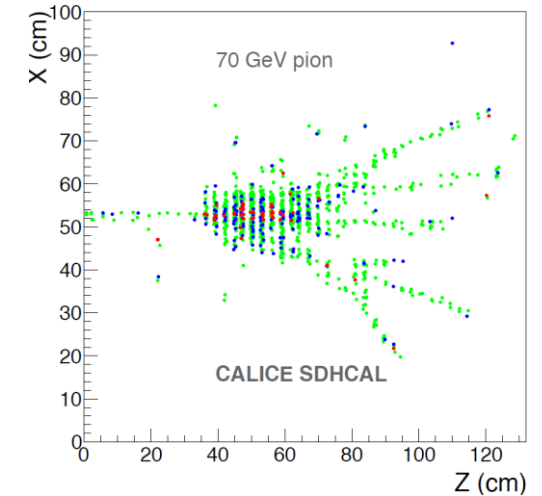
ASICs for DRD6

Christophe de LA TAILLE

Name	Track	Active media	readout
LAr	2	LAr	cold/warm elx"HGCROC/CALICElike ASICs"
ScintCal	3	several	SiPM
Cryogenic DBD	3	several	TES/KID/NTL
HGCC	3	Crystal	SiPM
MaxInfo	3	Crystals	SIPM
Crilin	3	PbF2	UV-SiPM
DSC	3	PBBGlass+PbWO4	SiPM
ADRIANO3	3	Heavy Glass, Plastic Scint, RPC	SIPM
FiberDR	3	Scint+Cher Fibres	PMT/SiPM,timing via CAENFERS, AARDVARC-v3,DRS
SpaCal	3	scint fibres	PMT/SiPMSPIDER ASIC for timing
Radical	3	Lyso:CE, WLS	SiPM
Grainita	3	BGO, ZnWO4	SiPM
TileHCal	3	organic scnt. tiles	SiPM
GlassScintTile	1	SciGlass	SiPM
Scint-Strip	1	Scint.Strips	SiPM
T-SDHCAL	1	GRPC	pad boards
MPGD-Calo	1	muRWELL,MMegas	pad boards(FATIC ASIC/MOSAIC)
Si-W ECAL	1	Silicon sensors	direct withdedicated ASICS (SKIROCN)
Si/GaAS-W ECAL	1	Silicon/GaAS	direct withdedicated ASICS (FLAME, FLAXE)
DECAL	1	CMOS/MAPS	Sensor=ASIC
AHCAL	1	Scint. Tiles	SiPM
MODE	4	-	-
Common RO ASIC	4	-	common R/O ASIC Si/SiPM/Lar

- On-detector embedded electronics, low-power multi-channel ASICs
 - CALICE SKI/SPI/HARDROC, FLAME, CMS HGCROC, FCC Lar, FATIC...
 - Challenges : #channels, low power, digital noise, data reduction
- Off-detector electronics : fiber/crystal readout
 - Waveform samplers : DRS, Nalu AARD, LHCb spider...
 - Challenges : low power, data reduction
- Digital calorimetry : MAPs, RPCs...
 - DECAL, ALICE FOCAL, CALICE SDHCAL
 - MAPS for em CAL : eg ALPIDE ASIC for FOCAL, DECAL...
 - Challenges : #channels, low power, data reduction

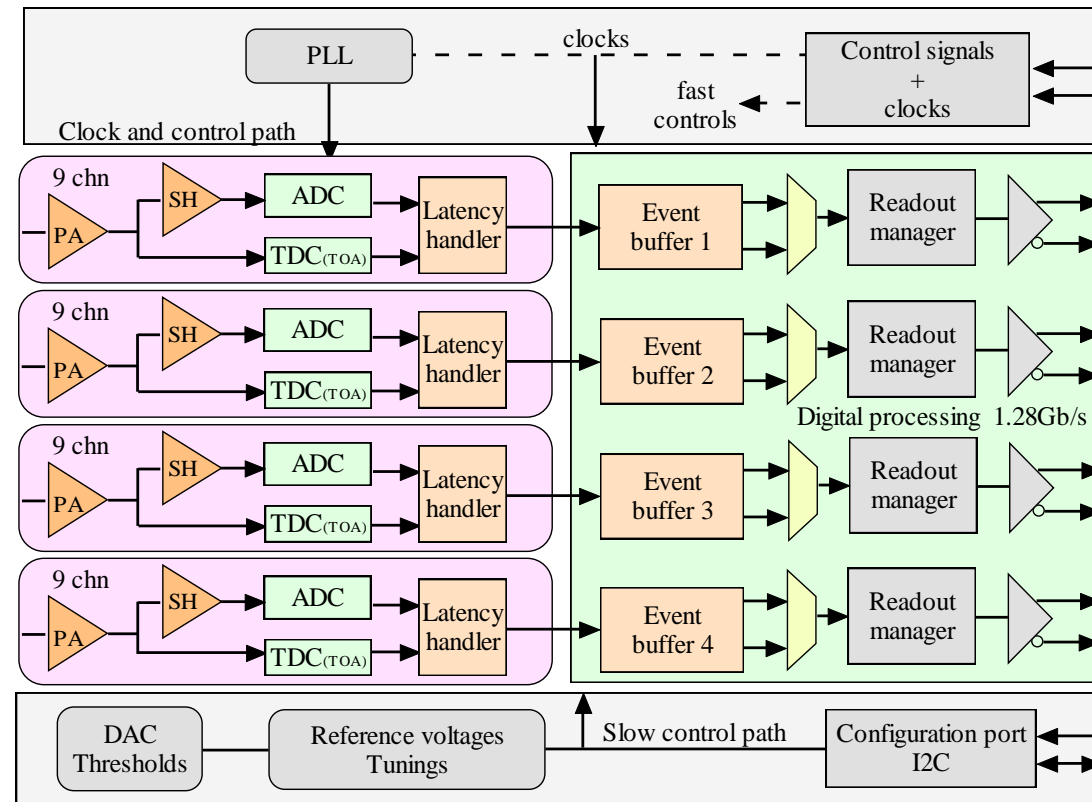
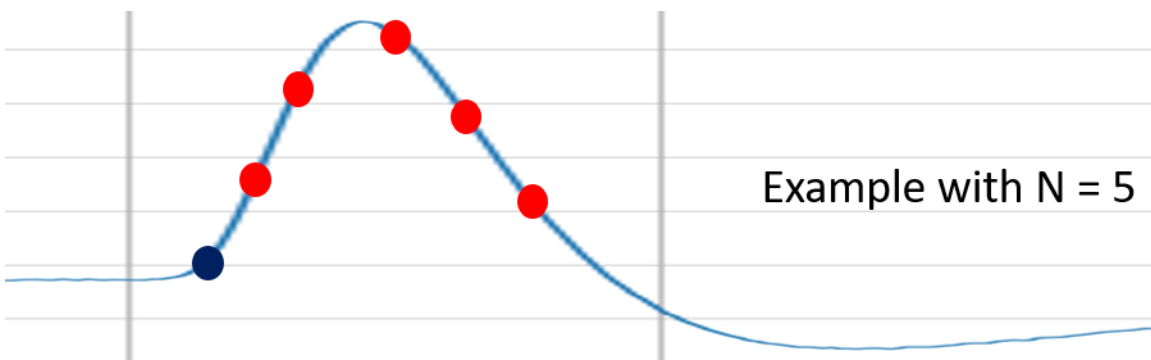
- Hadronic : e.g. CALICE RPCs or μ megas
 - $\sim 1 \text{ cm}^2$ pixels, low occupancy, $\sim 1 \text{ mW/cm}^2$
 - Performance improvement with semi-digital architecture
 - Timing capability can be added
- Electromagnetic : e.g. DECAL, ALICE FOCAL...
 - Based on ALPIDE : $(50\mu\text{m})^2$ pixels, high occupancy, \sim few 100mW/cm^2 , slow
 - To be compared with embedded electronics $\sim 10 \text{ mW/cm}^2$
 - Most power in digital processing \Rightarrow would benefit a lot from $\leq 28 \text{ nm}$ node
 - Semi-digital and/or larger pixels could be an interesting study



- Develop readout ASIC family for DRD6 prototype characterization
 - Inspired from CALICE SKIROC/SPIROC/HARDROC/MICROROC family
 - Targeting future experiments as mentioned in ICFA document (EIC, FCC, ILC, CEPC...)
 - Addressing **embedded electronics** and detector/electronics coexistence + **joint optimization**
 - Detector specific front-end but **common backend**
 - ⇒ allows common DAQ and facilitates combined testbeam
- Start from HGCROC / HKROC : Si and SiPM
 - **Reduce power** from 15 mW/ch to few mW/ch
 - Allows better granularity or LAr operation
 - Extend to LAr (cryogenic operation) and MCPs (PID)
 - Remove HL-LHC-specific digital part and provide flexible **auto-triggered** data payload
 - Several improvements foreseen in the VFE and digitization parts

HKROC : starting chip

- ❑ HKROC is 36 channels: 12 PMTs with High, Medium and Low gain
 - ❑ Or 36 PMTs with one gain
 - ❑ Charge measurement with 10 bit ADC
 - ❑ Time measurement with 25 ps binning
 - ❑ Readout with high speed links (1,28 Gb/s)
 - ❑ Hit rate ~400-1000 kHz/ch in average
 - ❑ Up to 20 consecutive events possible
 - ❑ Low power : 10 mW/ch
 - ❑ BGA package
 - ❑ HKROC is a waveform digitizer with auto-trigger and ps timing



- Common ASIC for time/charge measurement
 - Proposed as a service to allow detector characterization rather than electronics debugging
 - Common DAQ and easy combined tests
- Several other ASICs R/Os also developed and it is good !
 - FLAME/FLAXE, FATIC...
 - Waveform samplers : commercial or specific (SPIDER et al.)
 - DECAL
- Exchange on performance/issues inside DRD6 and DRD7
- Target (if possible) compatible I/Os : 40 MHz CK, I2C slow control, output levels...

c4. Interface with other DRDs

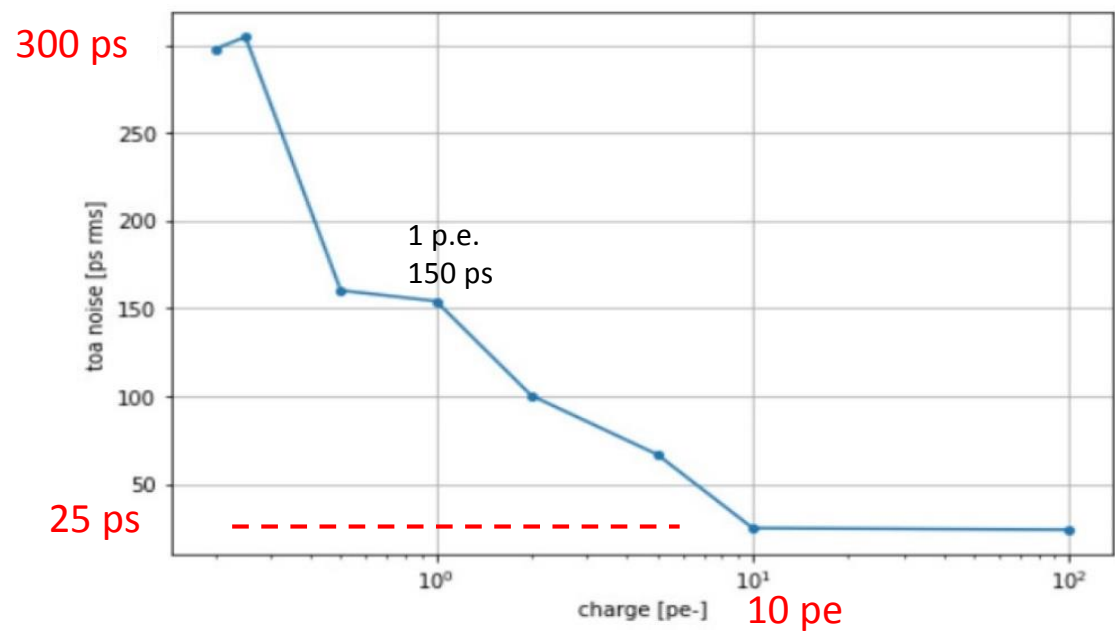
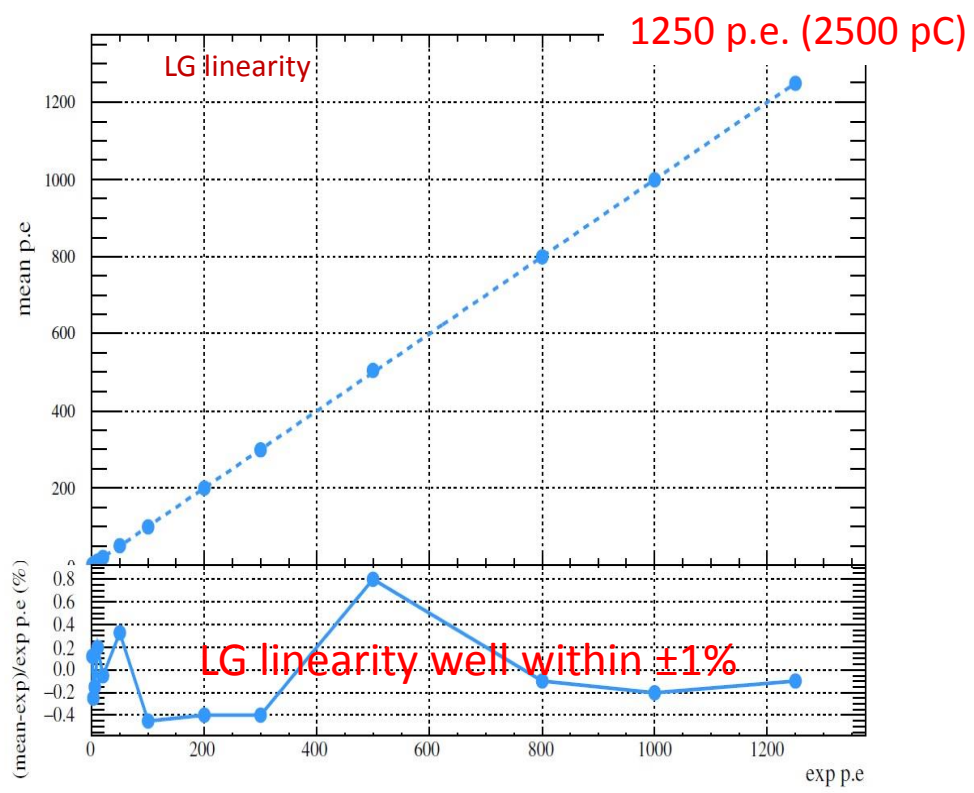
DRAFT, under discussion

- R&D in electronics is not carried out in isolation
 - Many engineers will be active in both DRD-specific projects and DRD7 generic R&D
 - DRD-specific projects will take care of
 - Determination of system parameters and specifications
 - Planning and costing of prototype development and production
 - Production, verification, and integration of ASICs and other project-specific components
 - Testing and operation of large-scale prototypes
 - DRD7 projects will
 - Review system specifications and design as requested, possibly also on a rolling basis during the course of the project, and including analysis of engineering effort and specialised skills requirements
 - Provision access to tools and vendors
 - Develop and provision common IP, components, and subsystems, encompassing hardware, firmware and software
 - Develop common, generic, complete components or systems, when too big or too complex to be designed in one single DRD
 - Provision specialised or large-scale facilities for electronic development and testing

- Importance of joint optimization detector/readout electronics
- Trend to reduce power and data volume
 - Pileup will be less of an issue
- Keep open all the different R/O options
- Provide common R/O ASICs when no specific development is required

Main experimental results with HKROC0 – Charge and Time

- Measurement with the full chain (analog + digital and reconstruction)
 - Signal auto-triggered with threshold



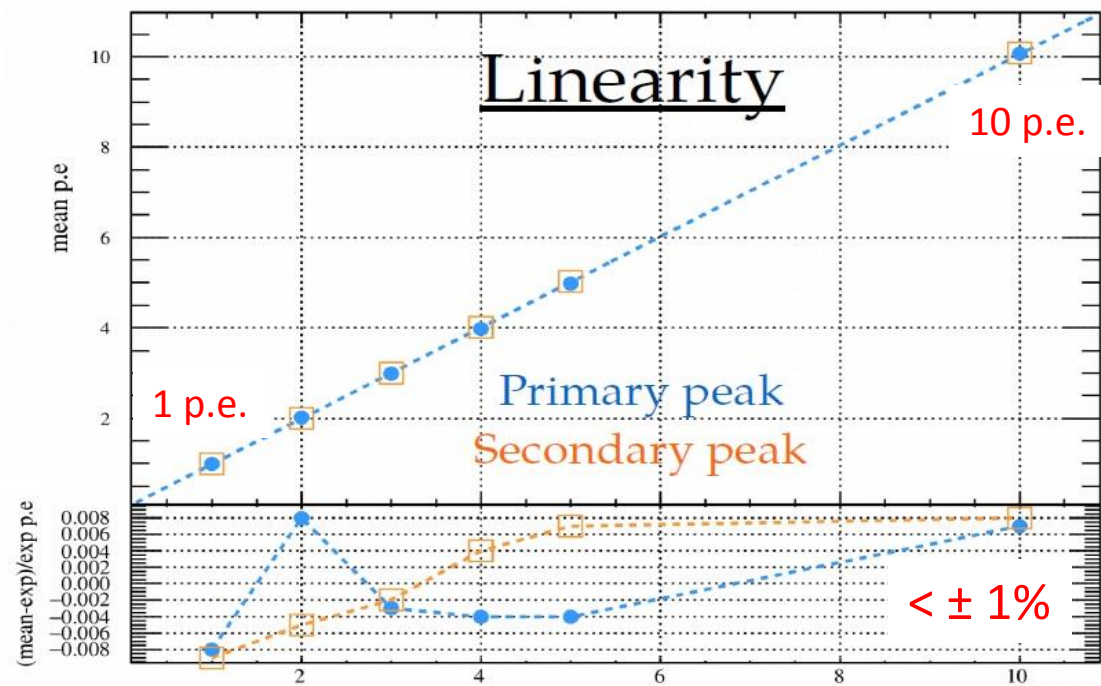
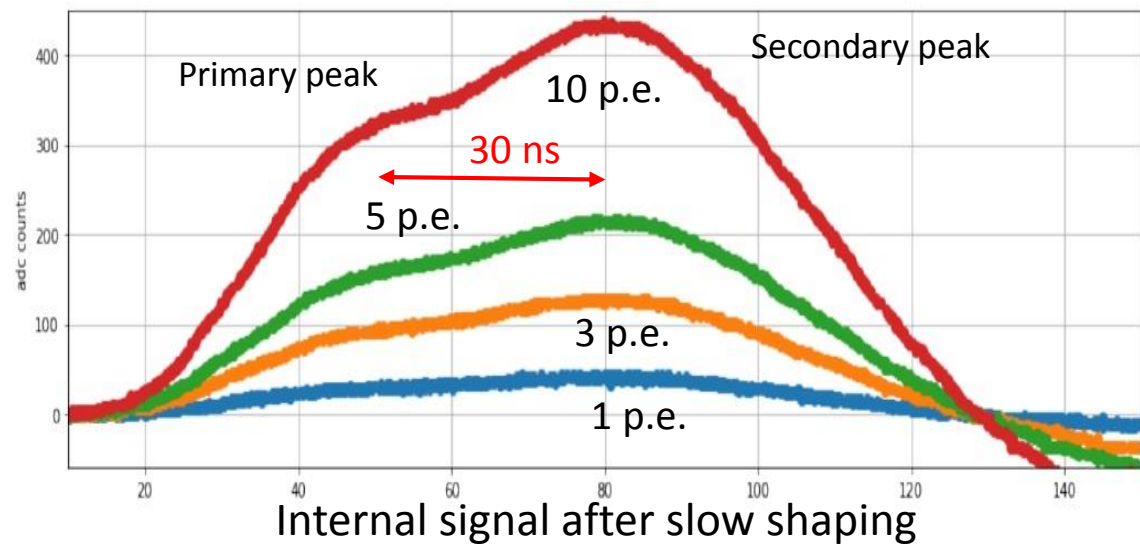
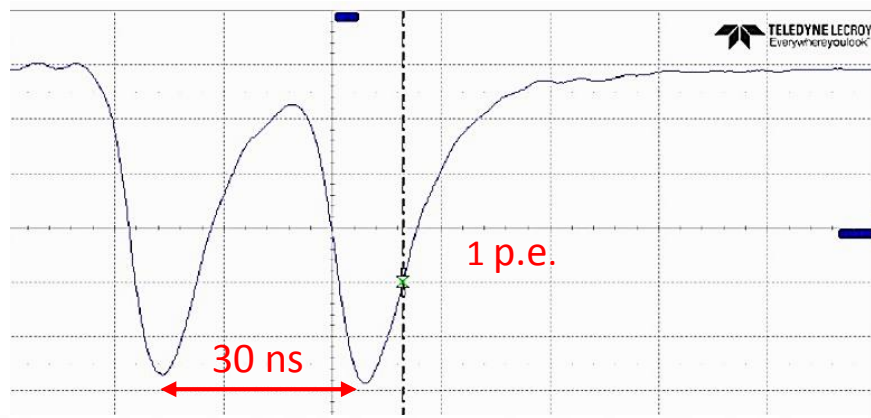
Charge resolution :
< **0.1 p.e (200 fC)** at ≤ 10 p.e
< **1 %** otherwise

Charge linearity < **$\pm 1\%$** from 1 to **1250 p.e. (2500 pC)** across the 3 gains

TDC characterization with **1/6 p.e. threshold**
TDC resolution :
150 ps rms @ 1 p.e
 ≤ 25 ps rms @ 10 p.e

Main experimental results with HKROC0 - Pile-up

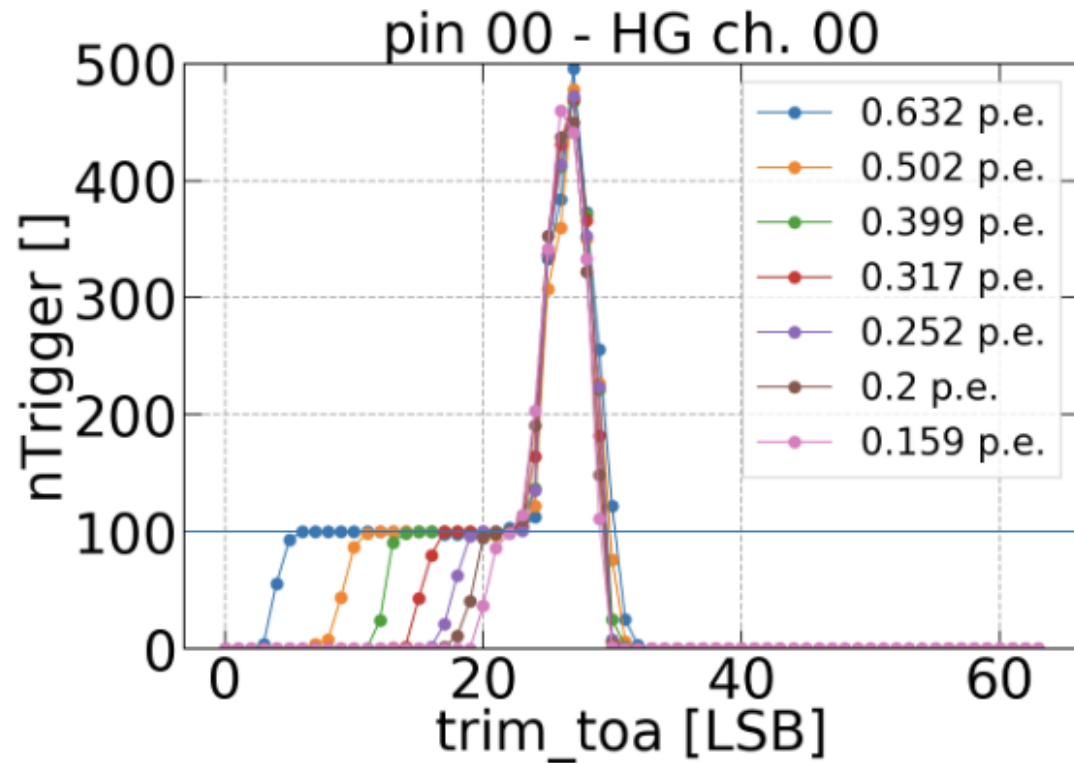
- Measurement with 2 events separated by ~ 30 ns (full chain: analog, digital and reconstruction)
- Signals auto-triggered (internal programmable threshold)



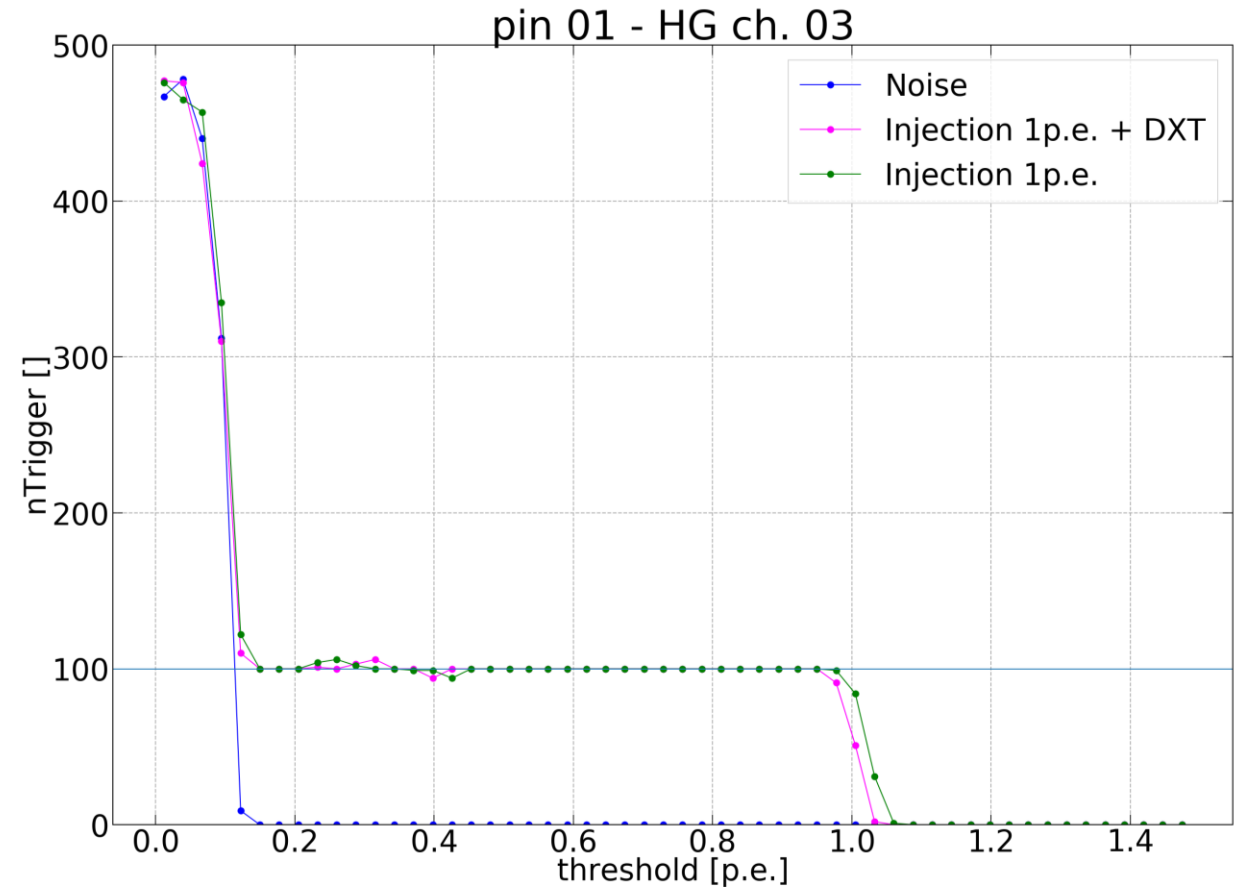
Charge reconstruction algorithm of the two peaks

Good linearity of reconstructed pile-up events

We can reconstruct both peaks properly !

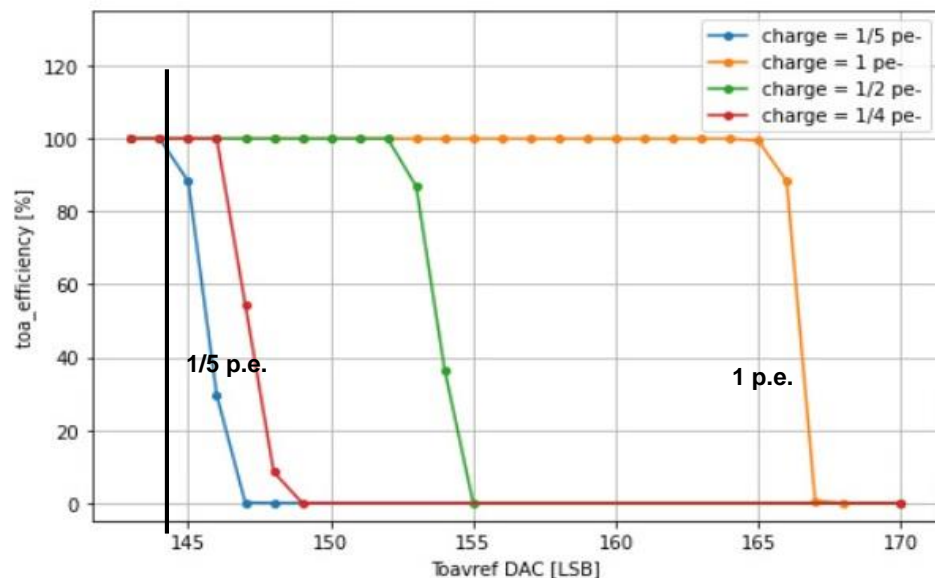


Minimum threshold of 1/6 pe

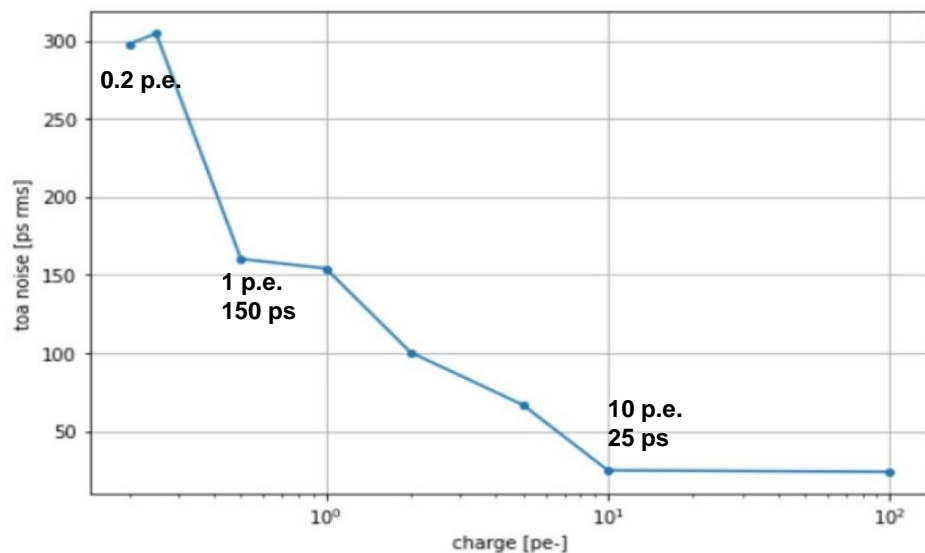


1 pe trigger efficiency with 1000 pe in another channel

The HyperK specifications require the trigger **threshold** to be set at **1/6 p.e (330 fC)**



- **Hit efficiency : 90 % for 1/5 p.e events (400fC)**
~100 % if $\geq 1/4$ p.e
- Extracted **threshold** value corresponding at **1/6 p.e**
- **Very low noise : < 1 Hz (0 noise hit in 10s @ 1/6 of p.e.)**

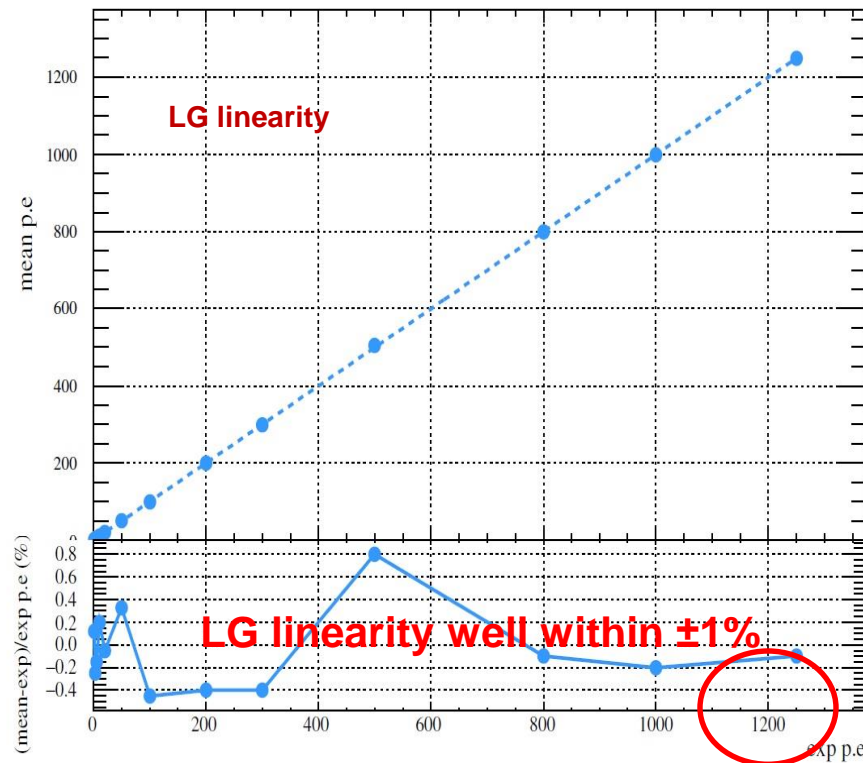


- TDC characterization with **1/6 p.e. threshold**
- TDC resolution :**
- **150 ps rms @ 1 p.e** [300 ps required]
 - ≤ 25 ps rms @ 10 p.e [200 ps required]

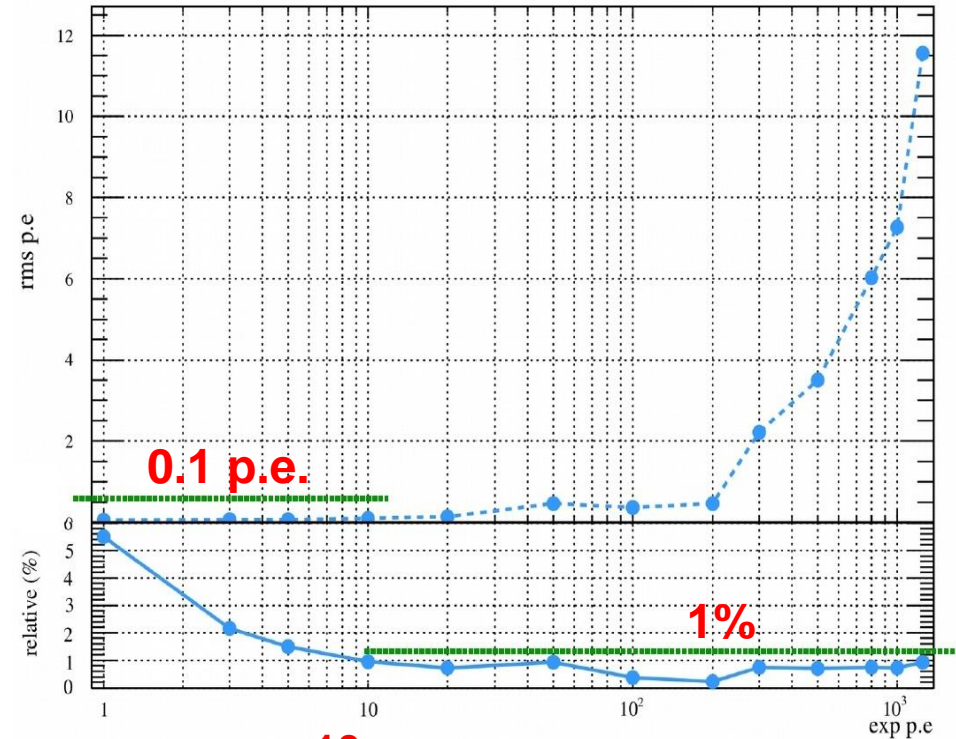
- Excellent agreement with HK requirements

The **whole** acquisition **chain** is tested:

The signal is **amplified, auto-triggered** and **converted** by the internal ADC.



1250 p.e. = 2500 pC



10 pe

1250 pe

HG, MG and LG tested!!

Charge linearity $< \pm 1\%$ from 1 to **1250 p.e. (2500 pC)**

The charge measurements Fulfill the HK requirements!!!

Charge resolution :

$< 0.1 \text{ p.e. (200 fC)}$ at $\leq 10 \text{ p.e.}$
 $< 1 \%$ otherwise